

SMAF Plastic-Encapsulate Diodes

High Efficient Rectifier

Features

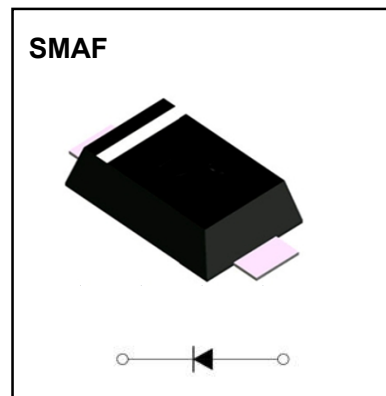
- I_o 2A
- V_{RRM} 50V-1000V
- High surge current capability
- Glass passivated chip
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- US2AF-US2MF : US2A-US2M



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	US2							
				AF	BF	DF	FF	GF	JF	KF	MF
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	300	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	210	280	420	560	700
Average Forward Current	$I_{F(AV)}$	A	60HZ Half-sine wave, Resistance load, $T_L = 110^\circ\text{C}$	2.0							
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave ,1 cycle , $T_a = 25^\circ\text{C}$	50							
Junction Temperature	T_J	$^\circ\text{C}$		-55~+150							
Storage Temperature	T_{STG}	$^\circ\text{C}$		-55~+150							

Electrical Characteristics ($T_a = 25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		US2						
					AF	BF	DF	FF	GF	JF	KF
Peak Forward Voltage	V _F	V	I _F =2.0A		1.0			1.3		1.7	
Maximum reverse recovery time	t _{tr}	ns	I _F =0.5A,I _R =1.0A,I _{tr} =0.25A		50				75		
Peak Reverse Current	I _{RRM1}	μA	V _{RM} =V _{RRM}	T _a =25℃	5.0						
	T _a =100℃			100							
Thermal Resistance(Typical)	R _{θJ-A}	℃/W	Between junction and ambient		80 ¹⁾						
	R _{θJ-L}		Between junction and terminal		20 ¹⁾						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

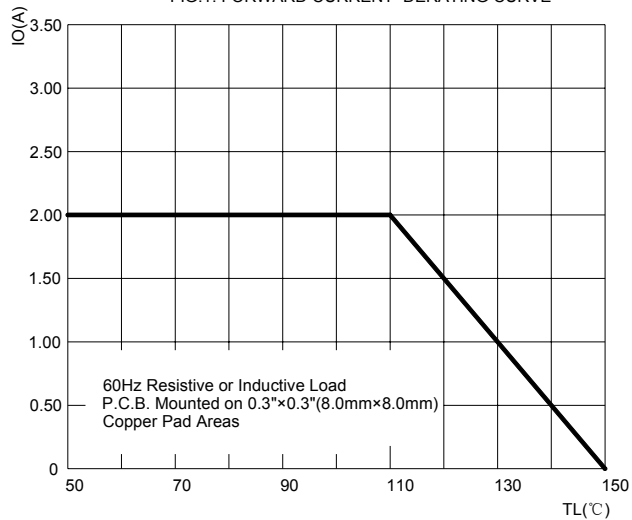


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

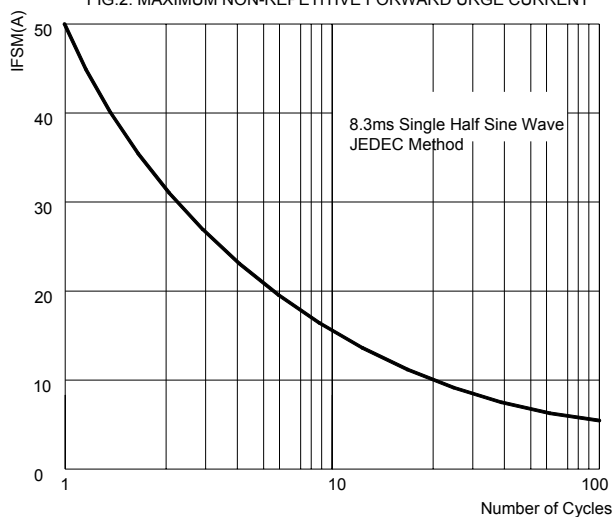


FIG.3: TYPICAL FORWARD CHARACTERISTICS

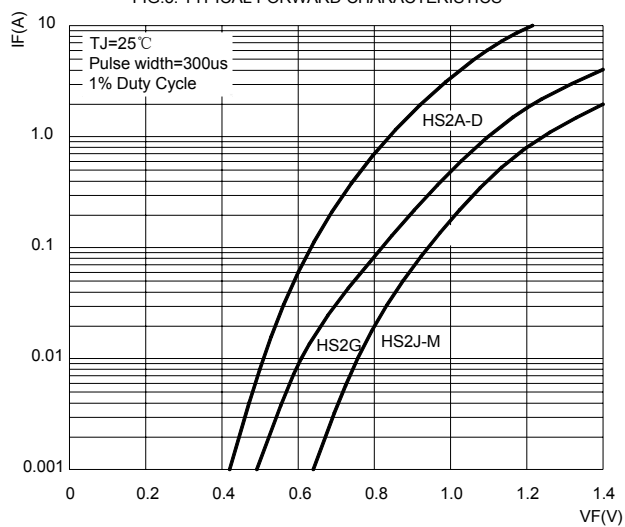


FIG.4: TYPICAL REVERSE CHARACTERISTICS

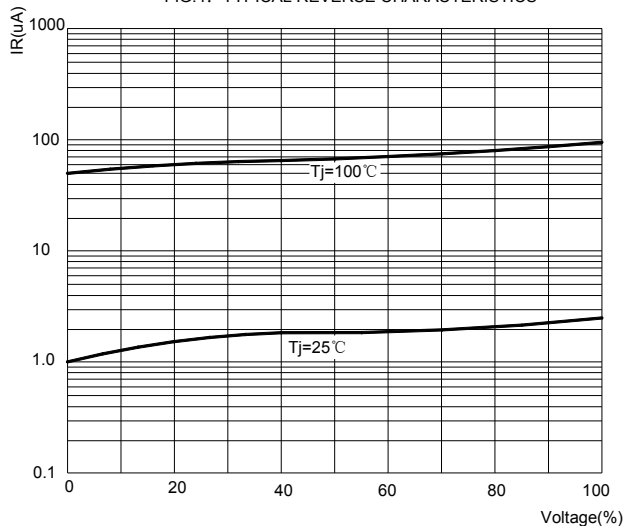
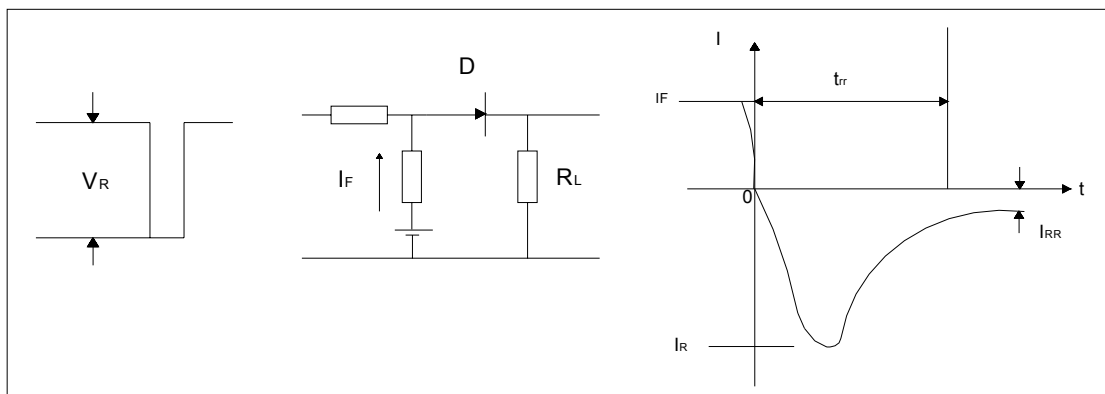
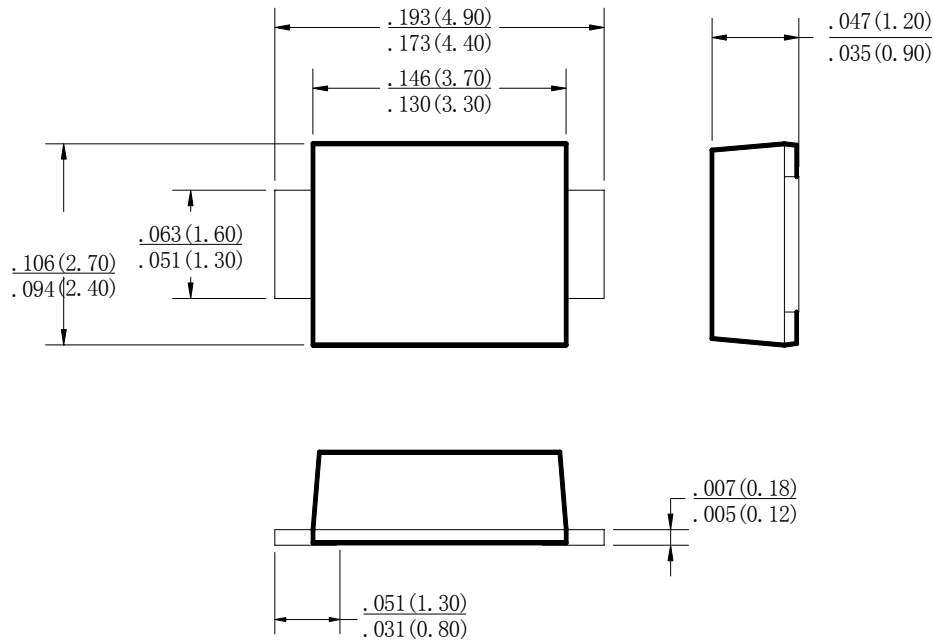


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

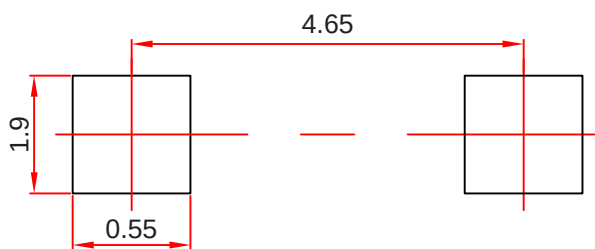


SMAF Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAF Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSHD does not assume any liability arising out of the application or use of any product described herein.

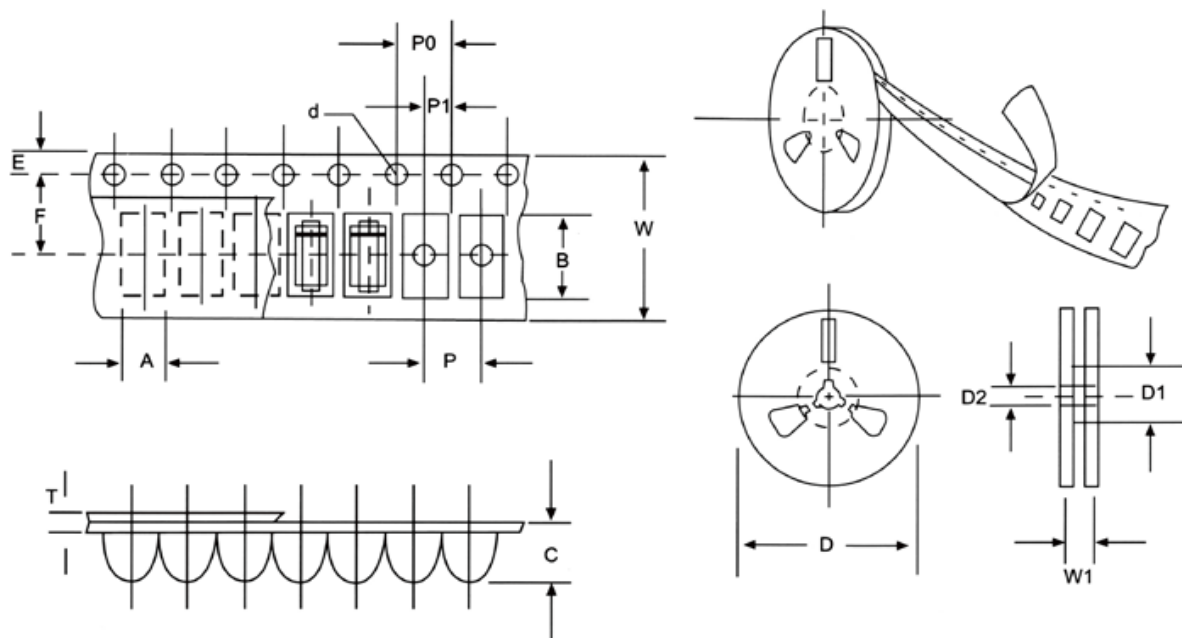


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMAF mm(inch)
Carrier width	A	2.83+0.1(0.112+0.004)
Carrier length	B	4.90+0.1(0.193+0.004)
Carrier depth	C	1.45+0.1(0.057+0.004)
Sprocket hole	d	1.55+0.05(0.061+0.002)
Reel outside diameter	D	280/178+2.0(11/7.0+0.079)
Reel inner diameter	D1	8.0+0.2(0.315+0.008)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Sprocket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.5+0.05(0.217+0.002)
Punch hole pitch	P	4.0+0.1(0.157+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Total tape thickness	T	0.23-0.29(0.009-0.011)
Tape width	W	12.0+0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.